

## PACKAGING & ASSEMBLY SERVICES

■ **Sub-contract design and assembly for optoelectronics and microelectronic devices**

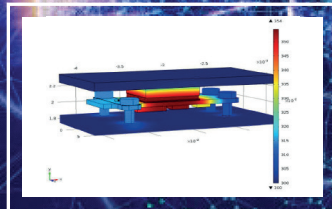
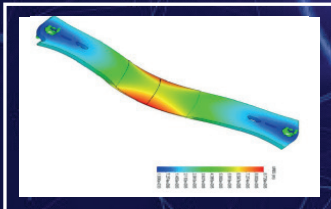
» Small batch prototypes through to volume manufacturing

■ **Design Services**

» Optical, mechanical & thermal modelling

» Advanced electro / optical package design

» Design for manufacture



■ **MIL-STD-883 and ESCC Standards Focussed areas of excellence**

» Wafer processing

» Precision placement and auto die attach

» Wire Bond – Au & Al, ball & wedge

» Hermetic sealing

» Optical alignment

» Laser packaging

» Photonic IC packaging

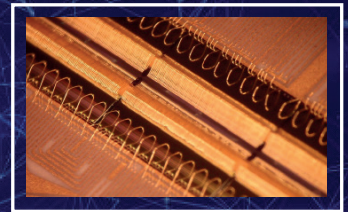
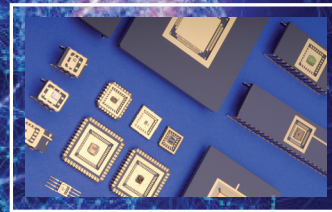
■ **Experienced end-to-end Manufacturer: wafer processing through to finished packaged product**

» ISO7 Clean Room assembly

» Optoelectronic & Optical Packaging

» Microelectronic & MEMS Packaging

» Electrical and optical test



» QC & Inspection

» Die shear and wire strength tests

» Real-time X-RAY

» Placement accuracy measurements

» Working with our parent Alter Technology to provide fully tested & qualified product solutions

» EEE procurement, Test, Screening & Qualification

